

Final Product Change Notification

Issue Date: 13-Feb-2020 Effective Date: 13-May-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

202001016F01

[] Product Marking



[]Test

Location

[X] Design

Management Summary

Transition from leadless HVSON package product TJA1145TK(/FD) to successor CAN FD drop-in replacement product TJA1145ATK(/FD)

Assembly

Process

[]

Change	Categ	jory

[] Wafer Fab Process

[]

] Wafer Fab Materials	[X]	[] Mechanical	[]Test	[] Errata
	Assembly	Specification	Process	
	Materials	•		
] Wafer Fab Location	[]	[]	[]Test	[X] Electrical
1	Assembly	Packing/Shipping/Labeling		
	Location	·	, _ q., p	coverage
				oovolago
] Firmware	[] Other			
Transition from Leadless HVSON				
Package Product TJA1145TK(/FD) to				
Successor CAN FD Drop-in				
Replacement Product				
TJÁ1145ATK(/FD)				

Description of Change

NXP Product Line In Vehicle Networking (PL IVN) recently informed you via Customer Information Notification (CIN) 201909013I of four design-related issues affecting product TJA1145. These could potentially affect your application using product TJA1145, and may cause failures or customer returns.

In October 2019 NXP PL IVN released the leadless HVSON package successor product TJA1145ATK(/FD), fulfilling additional CAN FD specifications as required by certain OEMs (5 Mbit/s timing, short Wake Up Pattern (WUP) and improved EMC). In this TJA1145ATK(/FD) product, before-mentioned four issues have been fixed through minor design changes. Note that the SO package product TJA1145AT(/FD) is planned to be released in Q4 2020 (above-mentioned CIN 201909013I incorrectly stated Q2 2020). A separate PCN for TJA1145AT(/FD) will be sent at that time.

This Product Change Notification (PCN) announces the transition from product TJA1145TK(/FD) to this drop-in replacement product TJA1145ATK(/FD). Apart from the design changes needed to fulfill the additional CAN FD requirements and to fix the before-mentioned issues, there is an industrial standardization to a copper (Cu) bondwire and associated mold compound change. For the new TJA1145ATK(/FD) the following holds: - Form: Only change is Cu wire, and associated change of mold compound - Fit: No change, TJA1145ATK(/FD) is a drop-in replacement for TJA1145TK(/FD)

- Function: Improved through fulfillment of additional datasheet CAN FD specifications
- Performance: Improved EMC
- Reliability: No change, product TJA1145ATK(/FD) is fully AEC-Q100 qualified and released

- Quality: Improved through minor design changes to fix before-mentioned four issues

The PCN for the SO package product TJA1145AT(/FD) will be sent in Q4 2020. Three months after that a separate formal Discontinuation Notification (DN) for the TJA1145 (both SO and leadless HVSON package product versions) will be sent, with a 1-year Last Time Buy (LTB) period, followed by a 1-year Last Time Shipment (LTS) period. This implies that you are required to act on this PCN, as you can no longer order the current non-A TJA1145 product after this period.

Attached to this PCN are documents that enable you to assess the change (qualification):

- A document with details on the change:

----- Between TJA1145 and TJA1145A datasheets

----- A migration guide, describing the drop-in replacement of TJA1145 with TJA1145A in your application

- A full AEC-Q100 qualification report for product TJA1145A
- The TJA1145A datasheet (only applicable for the leadless HVSON package version)
- The ZVEI Delta Qualification Matrix (DeQuMa) for this change

A PPAP and samples of product TJA1145ATK(/FD) are available on request. This information should enable you to transition to the new TJA1145ATK(/FD) product with a minor, if any, delta qualification.

Reason for Change

The successor product TJA1145ATK(/FD), fulfilling additional CAN FD specifications as required by certain OEMs, was already planned. This successor product TJA1145ATK(/FD) also contains minor design fixes for four issues that could potentially affect your application and may cause failures or customer returns.

The transition from the current product TJA1145TK(/FD) to the successor product TJA1145ATK(/FD), as announced by this Product Change Notification (PCN), is necessary to eliminate the risk for these failures or customer returns, and meet the OEM-required additional CAN FD specifications.

Identification of Affected Products

Top side marking

In the attachment to this PCN it is shown how the product name and the marking changes.

Product Availability

Sample Information Samples are available upon request Production

Planned first shipment 13-May-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

See above under heading 'Description of Change'.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

NotificationIssue DateEffective DateTitle201909013I06-Dec-201904-Jan-2020Important Information on Products UJA116x, UJA113x and TJA1145

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 14-Mar-2020. Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files': - An attachment with more detailed description of the change

- An AEC-Q100 reliability results report

- The TJA1145A datasheet

- A ZVEI Delta Qualification Matrix (DeQuMa) for the change, both in pdf and zipped excel format

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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NXP Quality Management Team.

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Affected Part Numbers	Changed Part 12NC	New Orderable Part#	New part 12NC
TJA1145TKJ	935301416118	TJA1145ATK/0Z	935361509431
TJA1145TK/FDJ	935301417118	TJA1145ATK/FD/0Z	935361508431